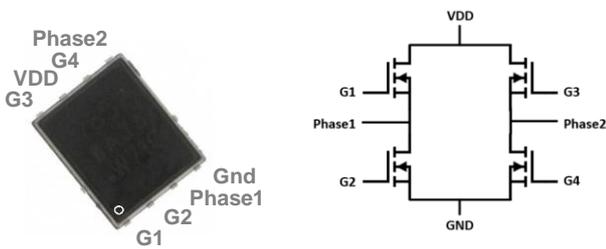


General Description

These Quad N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

| | | |
|-------|--------|-----|
| BVDSS | RDSON | ID |
| 30V | 15.5mΩ | 15A |

PPAK5x6 4 in 1 Pin Configuration



Features

- 30V, 15A, $R_{DS(ON)} = 15.5m\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Full Bridge Applications
- Wireless charger Applications

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|--|------------|---------------|
| V_{DS} | Drain-Source Voltage | 30 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| I_D | Drain Current – Continuous ($T_c=25^\circ C$) | 15 | A |
| | Drain Current – Continuous ($T_c=100^\circ C$) | 9.5 | A |
| I_{DM} | Drain Current – Pulsed ¹ | 60 | A |
| EAS | Single Pulse Avalanche Energy ² | 45 | mJ |
| IAS | Single Pulse Avalanche Current ² | 30 | A |
| P_D | Power Dissipation ($T_c=25^\circ C$) | 9.7 | W |
| | Power Dissipation – Derate above $25^\circ C$ | 0.08 | W/ $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 62 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | --- | 12.8 | $^\circ C/W$ |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Static State Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|--|--|------|------|------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 30 | --- | --- | V |
| ΔBV _{DSS} /ΔT _J | BV _{DSS} Temperature Coefficient | Reference to 25°C, I _D =1mA | --- | 0.04 | --- | V/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =30V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =24V, V _{GS} =0V, T _J =125°C | --- | --- | 10 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |
| R _{DS(ON)} | Static Drain-Source On-Resistance ³ | V _{GS} =10V, I _D =6A | --- | 13 | 15.5 | mΩ |
| | | V _{GS} =4.5V, I _D =5A | --- | 15 | 19 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 1.2 | 1.6 | 2.5 | V |
| ΔV _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | -4 | --- | mV/°C |
| gfs | Forward Transconductance | V _{DS} =10V, I _D =3A | --- | 6 | --- | S |

Dynamic Characteristics

| | | | | | | |
|---------------------|-------------------------------------|---|-----|------|------|----|
| Q _g | Total Gate Charge ^{3, 4} | V _{DS} =15V, V _{GS} =10V, I _D =6A | --- | 16.7 | 33 | nC |
| Q _{gs} | Gate-Source Charge ^{3, 4} | | --- | 4.5 | 8 | |
| Q _{gd} | Gate-Drain Charge ^{3, 4} | | --- | 1.3 | 2.6 | |
| T _{d(on)} | Turn-On Delay Time ^{3, 4} | V _{DD} =15V, V _{GS} =10V, R _G =3.3Ω I _D =15A | --- | 4.8 | 9 | ns |
| T _r | Rise Time ^{3, 4} | | --- | 12.5 | 24 | |
| T _{d(off)} | Turn-Off Delay Time ^{3, 4} | | --- | 27.6 | 52 | |
| T _f | Fall Time ^{3, 4} | | --- | 8.2 | 16 | |
| C _{iss} | Input Capacitance | V _{DS} =25V, V _{GS} =0V, F=1MHz | --- | 680 | 1000 | pF |
| C _{oss} | Output Capacitance | | --- | 150 | 220 | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 70 | 105 | |
| R _g | Gate resistance | V _{GS} =0V, V _{DS} =0V, F=1MHz | --- | 2.7 | 5.4 | Ω |

Drain-Source Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|------------------------------------|---|------|------|------|------|
| I _S | Continuous Source Current | V _G =V _D =0V, Force Current | --- | --- | 15 | A |
| I _{SM} | Pulsed Source Current ³ | | --- | --- | 30 | A |
| V _{SD} | Diode Forward Voltage ³ | V _{GS} =0V, I _S =1A, T _J =25°C | --- | --- | 1 | V |
| t _{rr} | Reverse Recovery Time | V _{GS} =0V, I _S =10A, di/dt=100A/μs | --- | 8.1 | --- | ns |
| Q _{rr} | Reverse Recovery Charge | T _J =25°C | --- | 1.6 | --- | nC |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=30A., R_G=25Ω, Starting T_J=25°C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

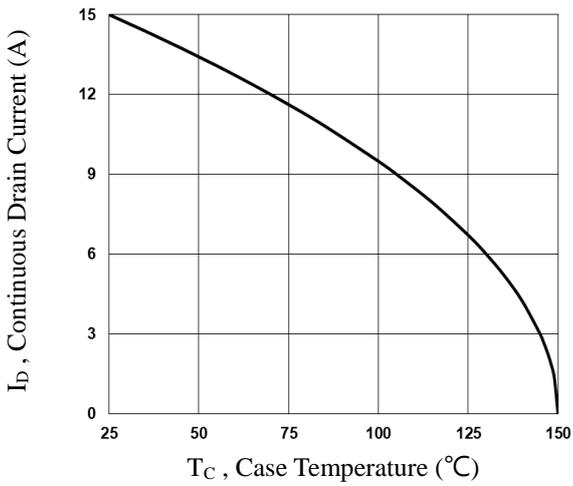


Fig.1 Continuous Drain Current vs. T_c

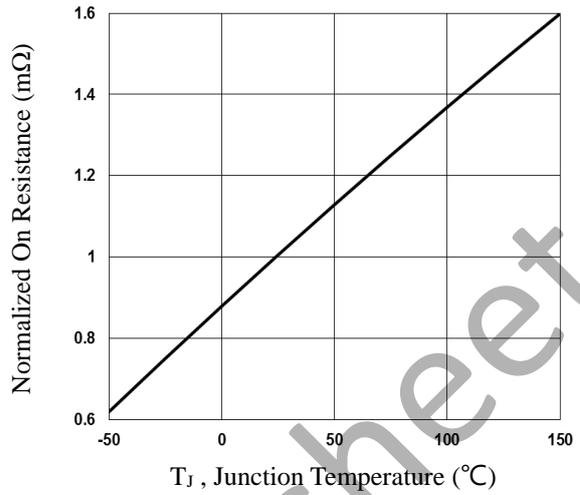


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

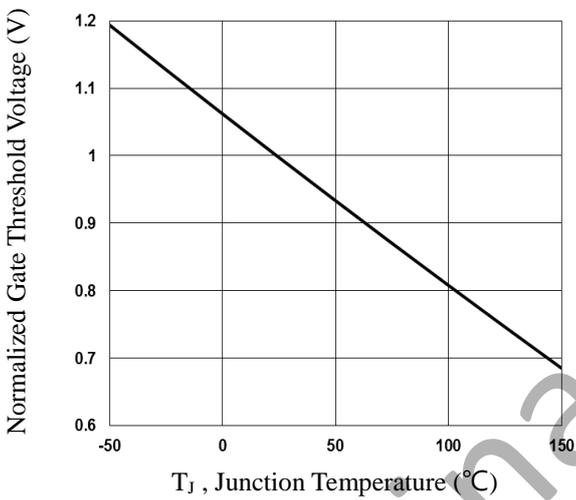


Fig.3 Normalized V_{th} vs. T_j

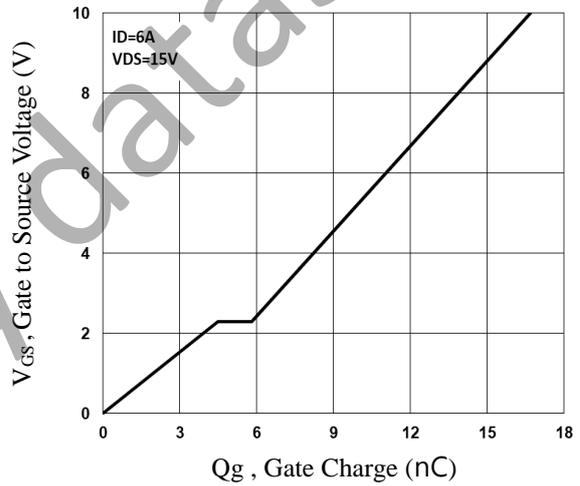


Fig.4 Gate Charge Waveform

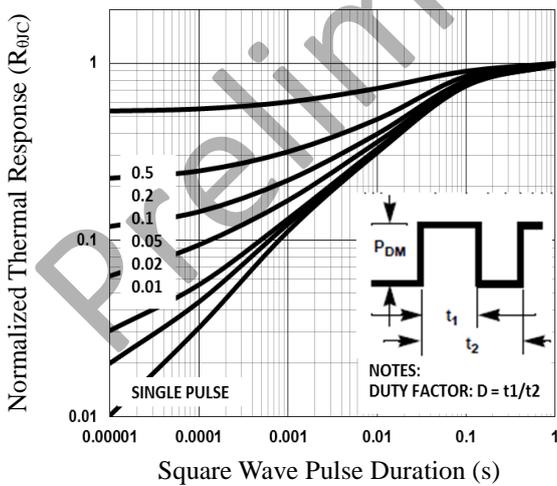


Fig.5 Normalized Transient Impedance

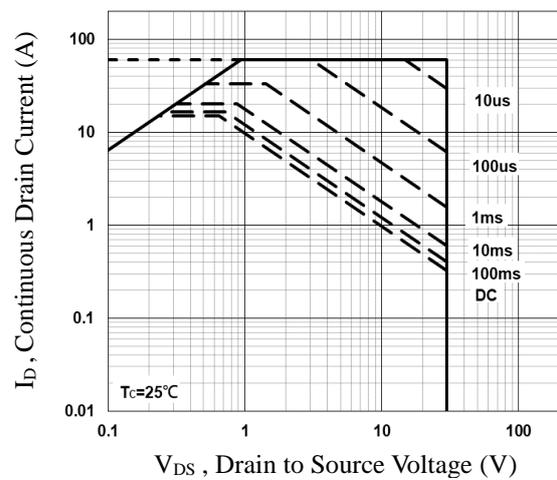


Fig.6 Maximum Safe Operation Area

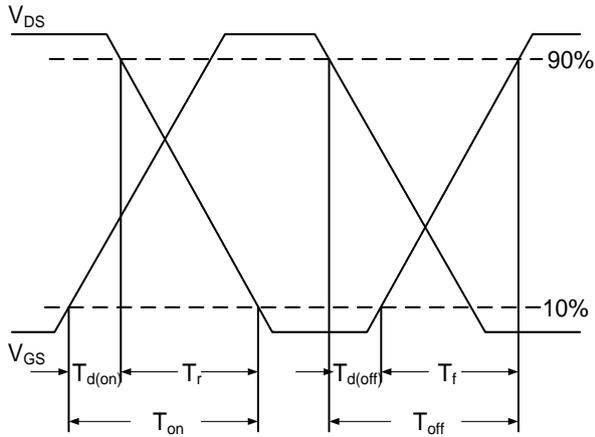


Fig.7 Switching Time Waveform

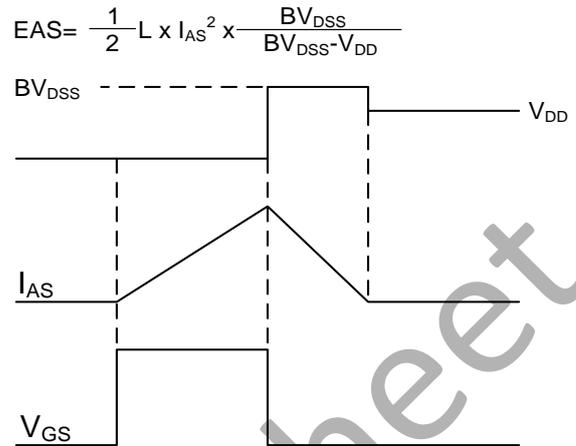


Fig.8 EAS Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

Preliminary datasheet

PPAK5x6 4 in 1 PACKAGE INFORMATION

